IC substrates & advanced packaging Technologies: key to the Computing systems of the Future

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The need for high performance and smarter devices with increased functionalities is driving the industry to develop new, innovative and advanced solutions. While scaling continues, the need for bringing in more functionalities into the package is driving the increased adoption of chiplets and heterogeneous integration. With the increase in high performance computing, the need for more advanced substrates has become more critical, from technology as well as supply chain availability especially in Europe.
AT&S is the first European IC substrate and PCB manufacturer to build up a small volume line and R&D line focusing on IC substrate and advanced packaging at its headquarter in Leoben, Austria as part of the IPCEI ME/CT. The combination of production and dedicated R&D area the highly complex processes are being developed for the next generations of heterogeneous integrated solutions in a wide range of applications.
The current presentation will focus on market drivers, industry challenges and solutions that AT&S is bringing to the market to address next generation industry needs.